

MSP430F5529 Device Erratasheet

1 Revision History

 \checkmark The check mark indicates that the issue is present in the specified revision.

The revision of the device can be identified by the revision letter on the Package Markings or by the HW_ID located inside the TLV structure of the device

Errata Number	Rev I	Rev H	Rev G	Rev F	Rev E	Rev D	Rev C
ADC25	_ ✓						_ ✓
ADC27	-	-	-	-	1	1	✓ ✓
ADC29					1		
BSL6		1	1	✓			
BSL7	1	1	✓	1	1	✓	✓
CPU26	1	1	\checkmark	1	1	✓	
CPU27	~	\checkmark	✓	\checkmark	\checkmark	\checkmark	✓
CPU28	1	✓	1	✓	✓	J J	✓
CPU29	1	✓	\checkmark	\checkmark	\checkmark	\checkmark	✓
CPU30	\checkmark	1	\checkmark	1	\checkmark	\checkmark	✓
CPU31	1	1	\checkmark	1	\checkmark	\checkmark	✓
CPU32	✓	<	イ イ イ	√	\checkmark	\checkmark	\checkmark
CPU33	1	√ 	\checkmark	\checkmark	\checkmark	\checkmark	✓
CPU34	1	✓	\checkmark	✓	\checkmark	\checkmark	\checkmark
CPU35	1	1	\checkmark	✓	\checkmark	\checkmark	\checkmark
CPU37	~	✓	√ √ √	✓ ✓	\checkmark	\checkmark	\checkmark
CPU39	✓	\checkmark	\checkmark		\checkmark	\checkmark	\checkmark
CPU40	\checkmark	\checkmark	✓	1	\checkmark	\checkmark	✓
CPU43	\checkmark	\checkmark	1	\checkmark	\checkmark	\checkmark	✓
DMA4	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
DMA8	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
DMA10	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	✓
EEM9	\checkmark	\checkmark	✓	\checkmark	\checkmark	\checkmark	✓
EEM11	\checkmark	\checkmark	1	\checkmark	\checkmark	\checkmark	✓
EEM13	\checkmark	\checkmark	✓	✓ ✓	\checkmark	\checkmark	\checkmark
EEM14	\checkmark	1	\checkmark	\checkmark	\checkmark	\checkmark	✓
EEM15	\checkmark	√	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
EEM16	1	\checkmark	ノ ノ ノ ノ ノ ノ ノ ノ ノ ノ ノ ノ ノ ノ	✓ ✓ ✓ ✓	1	J J	\checkmark
EEM17	1	1	1	1	1	1	\checkmark
EEM19	\checkmark	\checkmark	\checkmark	✓	\checkmark	\checkmark	\checkmark
EEM21	\checkmark	1	\checkmark	\checkmark	1	\checkmark	\checkmark
EEM23	\checkmark	✓	\checkmark	✓ ✓ ✓	1	\checkmark	\checkmark
FLASH33	1	✓		\checkmark	✓	\checkmark	J J <t< td=""></t<>
FLASH34	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark



Revision History

FLASH35 FLASH37	RevI	Rev	Rev G	Rev	Rev		
FLASH37					Ľ.	Rev	Rev C
						✓ ✓	✓ ✓ <td< td=""></td<>
JTAG20					\checkmark		\checkmark
	~	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
MPY1	\checkmark	\checkmark	\checkmark	\checkmark	>	\checkmark	\checkmark
	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
PMM9	✓	\checkmark	>	\checkmark	\checkmark	✓ ✓	\checkmark
PMM10					\checkmark		\checkmark
PMM11	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
PMM12	✓	\checkmark	\checkmark	>	>	~	\checkmark
PMM14	< <	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
PMM15	✓	\checkmark	~	\checkmark	\checkmark	✓ ✓	\checkmark
PMM17					\checkmark	\checkmark	\checkmark
PMM18	\checkmark	\checkmark	~	\checkmark	\checkmark	~	\checkmark
PMM20	~	\checkmark	>	>	\checkmark	>	\checkmark
PORT15	\checkmark	\checkmark	>	>	>	>	\checkmark
PORT16	✓ ✓ ✓	\checkmark	> > >	\checkmark	\checkmark	\checkmark	\checkmark
PORT19	✓	✓ ✓ ✓	\checkmark	✓✓	✓	✓✓	\checkmark
RTC3	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
RTC6	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
SYS10					\checkmark	\checkmark	\checkmark
SYS12							\checkmark
SYS16	✓	\checkmark	\checkmark	\checkmark	✓ ✓	✓ ✓	\checkmark
SYS18	✓ ✓ ✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
TAB23	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
UCS6			\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
UCS7	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
UCS9	✓	\checkmark	\checkmark	\checkmark	√	\checkmark	\checkmark
UCS10					\checkmark	\checkmark	\checkmark
UCS11	✓	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
USB4					\checkmark	\checkmark	\checkmark
USB6					\checkmark	\checkmark	\checkmark
USB8					\checkmark	\checkmark	✓
USB9			~	\checkmark	~	~	1
USB10	✓	✓	~	√	√	√	1
USCI26	✓		~	~	~	~	~
	✓	く く く	1	✓			\checkmark
USCI31	✓	√	✓ ✓	~	✓ ✓	✓✓	\checkmark
USCI34	✓	· √	√	✓	√	√ _	\checkmark
USCI35	< < < < <	√	√	√	✓	✓	✓ ✓ ✓ ✓ ✓
WDG4	✓	√	√	√	✓	✓	1

TEXAS INSTRUMENTS

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2 Package Markings

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PN80
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LQFP (PN), 80 Pin

♥ YMLLLLS M430Fxxx REV #	YM = Year and Month Date Code LLLL = LOT Trace Code S = Assembly Site Code # = DIE Revision o = PIN 1
VMLLLL <u>G4</u> M430Fxxxx Rev #	 YM = Year and Month Date Code LLLL = LOT Trace Code S = Assembly Site Code # = DIE Revision o = PIN 1

3 TLV Hardware Revision

Die Revision	TLV Hardware Revision
Rev I	18h
Rev H	17h
Rev G	16h
Rev F	15h
Rev E	14h
Rev D	N/A
Rev C	N/A

Further guidance on how to locate the TLV structure and read out the HW_ID can be found in the device User's Guide.

4 Detailed Bug Description

ADC25	ADC12_A Module
Function	Write to ADC12CTL0 triggers ADC12 when CONSEQ = 00
Description	If ADC conversions are triggered by the Timer_B module and the ADC12 is in single- channel single-conversion mode (CONSEQ = 00), ADC sampling is enabled by write access to any bit(s) in the ADC12CTL0 register. This is contrary to the expected behavior that only the ADC12 enable conversion bit (ADC12ENC) triggers a new ADC12 sample.
Workaround	When operating the ADC12 in CONSEQ=00 and a Timer_B output is selected as the sample and hold source, temporarily clear the ADC12ENC bit before writing to other bits in the ADC12CTL0 register. The following capture trigger can then be re-enabled by setting ADC12ENC = 1.
ADC27	ADC12_A Module
Function	Integral and differential non-linearity exceed specifications
Description	The ADC12_A integral and differential non-linearity may exceed the limits specified in the data sheet under the following conditions:
	- If the internal voltage reference generator is used
	and
	- If the reference voltage is not buffered off-chip
	and
	- If fADC12CLK > 2.7 MHz
	The non-linearity can be up to tens of LSBs. This is due to the internal reference buffer providing insufficient drive for the switched capacitor array of the ADC12_A.
Workaround	(1) Turn on the output of the internal voltage reference to increase the drive strength of the reference to the ADC_12 core:
	 If REFMSTR bit in REFCTL0 is 0 (allowing Shared REF to be controlled by ADC_A reference control bits)
	Set ADC12REFON bit in ADC12CTL0 = 1
	and
	Set ADC12REFOUT bit in ADC12CTL2 = 1
	- If REFMSTR bit in REFCTL0 is 1
	Set REFON and REFOUT bits in REFCTL0 = 1
	(2) Ensure fADC12CLK < 2.7 MHz. Depending on the frequency of the source of fADC12CLK (ACLK, MCLK, SMCLK, or MODOSC), select the divider bits accordingly.
	- If fADC12CLK = MODOSC
	(ADC12OSC) ADC12CTL1 = ADC12DIV_1; // Divide clock by 2
	- If fADC12CLK = ACLK/SMCLK/MCLK > 2.7 MHz.
	Use ADC12DIVx and/or ADC12PDIVx bits to reduce the selected clock frequency to between 0.45 MHz and 2.7 MHz.

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ADC29	ADC12_A Module
Function	Incorrect temperature sensor calibration data
Description	In some devices, the internal temperature sensor calibration data for 30 degC are invalid for all VRef conditions. Devices with correct calibration data show a difference of at least 30 LSBs between the different VRef conditions. When using incorrect calibration data with the internal temperature sensor ADC samples, the calculated results can be unreliable. Calibration data for 85 degC are not affected.
	MSP430F552x/551x/532x/524x silicon revision E devices with the lot trace code beyond 0BCVXPK are not affected by this erratum.
Workaround	Recalibrate the temperature sensor for 30 degC at the application level.
BSL6	BSL Module
Function	USB BSL does not respond properly to suspend/reset events from the USB host
Description	The USB BSL in affected revisions contains an improper configuration of the USB module. As a result, errors might occur in response to suspend/reset events from the USB host. (Since enumeration of the USB device often involves suspend and/or reset events, an enumeration might trigger the failure.) If the failure occurs, the device becomes unresponsive to the USB host.
	If the failure occurs, and if application code exists in main flash, a reset (BOR/POR/PUC) can be issued to switch execution away from the BSL, to the application. Given the same USB host/setup circumstances, the problem is likely to occur again on subsequent attempts.
	Applications that do not use the USB BSL are unaffected.
Workaround	1. The BSL can be updated via JTAG with a version that does not contain this bug. Use the code published in <ulink="www.ti.com lit="" pdf="" slaa450"="">BSL documentation starting with version 00.07.85.36.</ulink="www.ti.com>
BSL7	BSL Module
Function	BSL does not start after waking up from LPMx.5
Description	When waking up from LPMx.5 mode, the BSL does not start as it does not clear the Lock I/O bit (LOCKLPM5 bit in PM5CTL0 register) on start-up.
Workaround	 Upgrade the device BSL to the latest version (see Creating a Custom Flash-Based Bootstrap Loader (BSL) Application Note - SLAA450 for more details) OR Do not use LOCKLPM5 bit (LPMx.5) if the BSL is used but cannot be upgraded.
CPU26	CPUXv2 Module
Function	CALL SP does not behave as expected
Description	When the intention is to execute code from the stack, a CALL SP instruction skips the first piece of data (instruction) on the stack. The second piece of data at SP+2 is used as the first executable instruction.



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Workaround	Write the op code for a NOP as the first instruction on the stack. Begin the intended subroutine at address SP + 2.
CPU27	CPUXv2 Module
Function	Program Counter (PC) is corrupted during the context save of a nested interrupt
Description	When a low power mode is entered within an interrupt service routine that has enabled nested interrupts (by setting the GIE bit), and the instruction that sets the low power mode is directly followed by a RETI instruction, an incorrect value of PC + 2 is pushed to the stack during the context save. Hence, the RETI instruction is not executed on return from the nested interrupt and the PC becomes corrupted.
Workaround	Insert a NOP orno_operation() intrinsic function between the instruction that sets the lower power mode and the RETI instruction.
CPU28	CPUXv2 Module
Function	PC is corrupted when using certain extended addressing mode combinations
Description	An extended memory instruction that modifies the program counter executes incorrectly when preceded by an extended memory write-back instruction under the following conditions:
	First instruction:
	2-operand instruction, extended mode using (register,index), (register,absolute), OR (register,symbolic) addressing modes
	Second instruction:
	2-operand instruction, extended mode using the (indirect,PC), (indirect auto- increment,PC), OR (indexed [with ind 0], PC) addressing modes
	Example:
	BISX.A R6,&AABCD
	ANDX.A @R4+,PC
Workaround	1. Insert a NOP or ano_operation() intrinsic function between the two instructions Or
	2. Do not use an extended memory instruction to modify the PC
CPU29	CPUXv2 Module
Function	Using a certain instruction sequence to enter low power mode(s) affects the instruction width of the first instruction in an NMI ISR
Description	If there is a pending NMI request when the CPU enters a low power mode (LPMx) using an instruction of Indexed source addressing mode, and that instruction is followed by a 20-bit wide instruction of Register source and destination addressing modes, the first instruction of the ISR is executed as a 20-bit wide instruction.
	Example:
	main:
	MOV.W [indexed].SR : Enter LPMx

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	MOVX.A [register],[register]; 20-bit wide instruction
	ISR_start:
	MOV.B [indexed], [register]; ERROR - Executed as a 20-bit instruction!
	Note: [] indicates addressing mode
Workaround	 Insert a NOP or ano_operation() intrinsic function following the instruction that enters the LPMx using indexed addressing mode
	OR
	2. Use a NOP or aoperation() intrinsic function as first instruction in the ISR
	OR
	3. Do not use the indexed mode to enter LPMx
CPU30	CPUXv2 Module
Function	ADDA, SUBA, CMPA [immediate], PC behave as if immediate value were offset by -2
Description	The extended address instructions ADDA, SUBA, CMPA in immediate addressing mode are represented by 4-bytes of opcode (see the MSP430F5xx Family User's Guide <u>MSP430F5xx Family User's Guide</u> for more details). In cases where the program counter (PC) is used as the destination register only 2 bytes of the current instruction's 4-byte opcode are accounted for in the PC value. The resulting operation executes as if the immediate value were offset by a value of -2.
	Ideal: ADDA #Immediate-4, PC
	is equivalent to
	Actual: ADDA #Immediate-2, PC
	** NOTE: The MOV instruction is not affected **
Workaround	 Modify immediate value in software to account for the offset of 2. OR
	2) Use extended 20-bit instructions (addx.a, subx.a, cmpx.a).
CPU31	CPUXv2 Module
Function	SP corruption
Description	When the instruction PUSHX.A is executed using the indirect auto-increment mode with the stack pointer (SP) as the source register [PUSHX.A @SP+] the SP is consequently corrupted. Instead of decrementing the value of the SP by four, the value of the SP is replaced with the data pointed to by the SP previous to the PUSHX.A instruction execution.
Workaround	None. The compiler will not generate a PUSHX.A instruction that involves the SP.
CPU32	CPUXv2 Module
Function	CALLA PC executes incorrectly
Description	When the instruction CALLA PC is executed, the program counter (PC) that is pushed

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	onto the stack during the context save is incorrectly offset by a value of -2.
Workaround	None. The compiler will not generate a CALLA PC instruction.
CPU33	CPUXv2 Module
Function	CALLA [indexed] may corrupt the program counter
Description	When the Stack Pointer (SP) is used as the destination register in the CALLA index(Rdst) instruction and is preceded by a PUSH or PUSHX instruction in any of the following addressing modes: Absolute, Symbolic, Indexed, Indirect register or Indirect auto increment, the "index" of the CALLA instruction is not sign extended to 20-bits and is always treated as a positive value. This causes the Program Counter to be set to a wrong address location when the index of the CALLA instruction represents a negative offset.
	NOTE: 1. This erratum only applies when the instruction sequence is: PUSH or PUSHX followed
	by CALLA index(SP)
	This erratum does not apply if the PUSH or PUSHX instruction is used in the Register or Immediate addressing mode
	3. This erratum only applies when SP is used as the destination register in the CALLA index(Rdst) instruction
Workaround	Place a "NOP" instruction in between the PUSH or PUSHX and the CALLA index(SP) instructions.
	NOTE: This bug has no compiler impact as the compiler will not generate a CALLA instruction that uses indexed addressing mode with the SP.
CPU34	CPUXv2 Module
Function	CPU may be halted if a conditional jump is followed by a rotate PC instruction
Description	If a conditional jump instruction (JZ, JNZ, JC, JNC, JN, JGE, JL) is followed by an Address Rotate instruction on the PC (RRCM, RRAM, RLAM, RRUM) and the jump is not performed, the CPU is halted.
Workaround	Insert a NOP between the conditional jump and the rotate PC instructions.
CPU35	CPUXv2 Module
Function	Instruction BIT.B @Rx,PC uses the wrong PC value
Description	The BIT(.B/.W) instruction in indirect register addressing mode uses the wrong PC value. This instruction is represented by 2 bytes of opcode. If the Program Counter (PC) is used as the destination register, the 2 opcode bytes of the current BIT instruction are not accounted for. The resulting operation executes the instruction using the wrong PC value and this affects the results in the Status Register (SR).
Workaround	None.
	Note: The compiler will not generate a BIT instruction that uses the PC as an operand.



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CPU37	CPUXv2 Module
Function	Wrong program trace display in the debugger while using conditional jump instructions
Description	The state storage window displays an incorrect sequence of instructions when:
	1. Conditional jump instructions are used to form a software loop
	AND
	2. A false condition on the jump breaks out of the loop
	In such cases the trace buffer incorrectly displays the first instruction of the loop as the instruction that is executed immediately after exiting the loop.
	Example:
	Actual Code:
	mov #4,R4
	LABEL mov #1,R5
	dec R4
	jnz LABEL
	mov #2,R6
	nop
	State Storage Window Displays:
	LABEL mov #1,R5
	dec R4
	jnz LABEL
	mov #1,R5
	nop
Workaround	None
	Note: This erratum affects the trace buffer display only. It does not affect code execution in debugger or free run mode
CPU39	CPUXv2 Module
Function	PC is corrupted when single-stepping through an instruction that clears the GIE bit
Description	Single-stepping over an instruction that clears the General Interrupt Enable bit (for example DINT or BIC #GIE,SR) when the GIE bit was previously set may corrupt the PC. For example, the DINT or BIC #GIE,SR is a 2-byte instruction. Single stepping through this instruction increments the PC by a value of 4 instead of 2 thus corrupting the next PC value.
	Note: This erratum applies to debug mode only.
Workaround	Insert a NOP orno_operation() intrinsic immediately after the line of code that clears the GIE bit.
CPU40	CPUXv2 Module



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Function	PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section
Description	If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in
	RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.
	For example, a conditional jump instruction followed by data section (0140h).
	@0x8012 Loop DEC.W R6
	@0x8014 DEC.W R7
	@0x8016 JNZ Loop
	@0x8018 Value1 DW 0140h
Workaround	In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.
CPU43	CPUXv2 Module
Function	Halt operation in debug mode may cause unintended behavior
Description	In certain cases when using the 'Halt CPU' function available via the IDE (CCS or IAR), on continuing code execution after a halt, the program counter may skip an instruction.
	Pausing and resuming code execution after a breakpoint works as expected and is not affected by the erratum.
	Note: This erratum affects debug mode only.
Workaround	None.
DMA4	DMA Module
Function	Corrupted write access to 20-bit DMA registers
Description	When a 20-bit wide write to a DMA address register (DMAxSA or DMAxDA) is interrupted by a DMA transfer, the register contents may be unpredictable.
Workaround	 Design the application to guarantee that no DMA access interrupts 20-bit wide accesses to the DMA address registers.
	OR
	 When accessing the DMA address registers, enable the Read Modify Write disable bit (DMARMWDIS = 1) or temporarily disable all active DMA channels (DMAEN = 0).
	OR
	3. Use word access for accessing the DMA address registers. Note that this limits the values that can be written to the address registers to 16-bit values (lower 64K of Flash).
DMA8	DMA Module



www.ti.com	Detailed Bug Description
Description	If the DMA controller makes a write access to the stack while executing one of the following instructions, the data that is written may be corrupted.
	CALLA [REG IDX SYM ABS IND INA IMM]
	PUSHX.A [IDX SYM ABS IND IMM INA]
	PUSHX.A [REG]
	PUSHM.A [REG]
	POPM.A [REG]
	Note: [] denotes an addressing mode
Workaround	Do not declare function-scope variables. Declare all variables that are intended to be modified by the DMA as global- or file-scope such that they are allocated in the data section of RAM and not on the program stack.
DMA10	DMA Module
Function	DMA interrupting CPU wait state might cause peripheral module into unknown state.
Description	When the CPU accesses a module that is capable of stalling the CPU with a wait mechanism, if a DMA interrupts the instruction during the CPU stall, the module might be caused into an unknown state.
	The affected modules (if present on the device) that can stall CPU are: FRAM controller in manual timing mode, MPY, CRC, USB, and RF1A.
	As an example a wrong result can be read by DMA from MPY result register because the DMA does not wait until MPY operation is finished.
Workaround	Disable DMA when using affected modules.
EEM9	EEM Module
Function	Combined triggers on the PUSH instruction may be missed
Description	When the PUSH instruction is used in any addressing mode except register or immediate modes, a combined trigger may be missed when its conditions are defined by a PUSH instruction fetch and a successful match of the value being pushed onto stack.
Workaround	None
EEM11	EEM Module
Function	Conditional register write trigger fails while executing rotate instructions
Description	A conditional register write trigger will fail to generate the expected breakpoint if the trigger condition is a result of executing one of the following rotate instructions: RRUM,RRCM, RRAM and RLAM.
Workaround	None
	Note: This erratum applies to debug mode only.
	EEM Module
EEM13	



Detailed Bug Description	www.ti.com					
Description	When debugging, if the device is in any low power mode and the debugger is halted, the program counter update by the debugger is corrupted. The debugger is unable to halt at the correct location.					
Workaround	None.					
	Note: This erratum applies to debug mode only.					
EEM14	EEM Module					
Function	Single-step or breakpoint on module registers with WAIT capability may not work					
Description	In debug mode, the CPU clock is driven independently from the wait inputs of device modules (i.e., MULT, USB, RF1A, CRC). As a result, an EEM halt on an access to the module data registers (breakpoint or single-step) may show incorrect results due to incomplete execution.					
Workaround	Do not single-step through a data register access that holds the CPU to provide a valid result. Place breakpoints after the affected register is accessed and sufficient clock cycles have been provided.					
	Note: This erratum applies to debug mode only.					
EEM15	EEM Module					
Function	Read or write to RF1A, CRC, MULT and USB RAM may be corrupted when debugging					
Description	When performing read or write operations on modules that require CPU wait cycles (i.e. when accessing CRC, RF1A, MULT and USB RAM) setting a breakpoint on or single stepping through the operation could corrupt the result.					
Workaround	None					
	Note: This erratum applies to debug mode only.					
EEM16	EEM Module					
Function	The state storage display does not work reliably when used on instructions with CPU Wait cycles.					
Description	When executing instructions that require wait states; the state storage window updates incorrectly. For example a flash erase instruction causes the CPU to be held until the erase is completed i.e. the flash puts the CPU in a wait state. During this time if the state storage window is enabled it may incorrectly display any previously executed instruction multiple times.					
	Note: This erratum affects debug mode only.					
Workaround	Do not enable the state storage display when executing instructions that require wait states. Instead set a breakpoint after the instruction is completed to view the state storage display.					
EEM17	EEM Module					
Function	Wrong Breakpoint halt after executing Flash Erase/Write instructions					
Description	Hardware breakpoints or Conditional Address triggered breakpoints on instructions that					

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	follow Flash Erase/Write instructions, stops the debugger at the actual Flash Erase/Write instruction even though the flash erase/write operation has already been executed. The hardware/conditional address triggered breakpoints that are placed on either the next two single opcode instructions OR the next double opcode instruction that follows the Flash Erase/Write instruction are affected by this erratum.			
	Note: This erratum affects debug mode only.			
Workaround	None. Use other conditional/advanced triggered breakpoints to halt the debugger right after Flash erase/write instructions.			
EEM19	EEM Module			
Function	DMA may corrupt data in debug mode			
Description	When the DMA is enabled and the device is in debug mode, the data transferred by the DMA may be corrupted when a breakpoint is hit or when the debug session is halted.			
	NOTE: This erratum applies to debug mode only.			
Workaround	None. Do not set a breakpoint during a DMA transfer.			
EEM21	EEM Module			
Function	LPMx.5 debug limitations			
Description	Debugging the device in LPMx.5 mode might wake the device up from LPMx.5 mode inadvertently, and it is possible that the device enters a lock-up condition; that is, the device cannot be accessed by the debugger any more.			
Workaround	Follow the debugging steps in Debugging MSP430 LPM4.5 <u>SLAA424</u> .			
EEM23	EEM Module			
Function	EEM functions do not work reliably when modules using wait cycles are enabled			
Description	When modules using wait states (USB, MPY,CRC and FRAM controller in manual mode) are enabled the EEM may not perform profile counter and state storage functions reliably.			
	Note: This erratum affects debug mode only.			
Workaround	Do not enable profile counter and state storage functions when modules using wait states are enabled.			
FLASH33	FLASH Module			
Function	Flash erase/program with fsystem <160kHz causes code execution to fail			
Description	A flash erase or flash program operation with the system frequency (fsystem) <160kHz causes the program execution (executing out of main or info memory) that follows to fail.			
Workaround	Make sure the fsystem >160kHz before doing a flash erase or program operation.			

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Detailed Bug Description

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FLASH34	FLASH Module
Function	Concurrent flash read during bank erase fails
Description	Code residing in flash cannot be executed during a bank erase.
Workaround	Place the code to be executed during bank erase in RAM.
FLASH35	FLASH Module
Function	Flash read error may cause invalid memory access
Description	Flash memory accesses are always 32-bit wide and performed on 32-bit boundaries. A read error when accessing flash may corrupt the second most significant bit (MSB-1) in a 32-bit access when programmed as a logic 0.
	When affected flash is idle, the read disturb may occur on the first flash access that follows any of the listed events:
	- On reset issued at RST input pin
	 On wakeup from low-power modes when executing interrupt service routines located at addresses <0xC400
	- When moving program execution from unaffected to affected areas of flash
	- When accessing affected flash after execution from RAM
Workaround	See Flash Read Error and Susceptibility for MSP430F55xx (SLAA471) for detailed
	background information and possible workaround(s).
FLASH37	FLASH Module
Function	Corrupted flash read when SVM low-side flag is triggered
Description	If the SVM low side is enabled, a change in the VCORE voltage level (an increase in the VCORE level) may cause the currently executed read operation from flash to be incorrect and may lead to unexpected code execution or incorrect data. This can happen under any one of the following conditions:
	- When the VCORE is changed in application, the SVM low side is used to indicate if the core voltage has settled by using the SVMDLYIFG flag. The failure occurs only when a flash access is concurrent to the expiration of the settling time delay.
	- Unexpected changes in the VCORE voltage level
	For code examples and detailed guidance on the PMM operation and software APIs for PMM configuration see the driverlib APIs from 430Ware (<u>MSP430Ware</u>).
Workaround	- Execute the procedure to change the VCORE level from RAM.
	or
	 If executing from flash, follow the procedure below when increasing the VCORE level. Note: To apply this workaround, the SVM low-side comparator must operate in normal mode (SVMLFP = 0 in SVMLCTL).
	// Set SVM highside to new level and check if a VCore increase is possible
	SVSMHCTL = SVMHE SVSHE (SVSMHRRL0 * level);
	// Wait until SVM highside is settled



www.ti.com	Detailed Bug Description
	while ((PMMIFG & SVSMHDLYIFG) == 0);
	// Clear flag
	PMMIFG &= ~SVSMHDLYIFG;
	// Set also SVS highside to new level
	// Vcc is high enough for a Vcore increase
	SVSMHCTL = (SVSHRVL0 * level);
	// Wait until SVM highside is settled
	while ((PMMIFG & SVSMHDLYIFG) == 0);
	// Clear flag
	PMMIFG &= ~SVSMHDLYIFG;
	//**********flow change for errata workaround ***********
	// Set VCore to new level
	PMMCTL0_L = PMMCOREV0 * level;
	// Set SVM, SVS low side to new level
	SVSMLCTL = SVMLE (SVSMLRRL0 * level) SVSLE (SVSLRVL0 * level);
	// Wait until SVM, SVS low side is settled
	while ((PMMIFG & SVSMLDLYIFG) == 0);
	// Clear flag
	PMMIFG &= ~SVSMLDLYIFG;
	//*********flow change for errata workaround ***********
JTAG20	JTAG Module
Function	BSL does not exit to application code
Description	The methods used to exit the BSL per MSP430 Programming Via the Bootstrap Loader (<u>SLAU319</u>) are invalid.
Workaround	To exit the BSL one of the following methods must be used.
	- A Power cycle
	or
	 Toggle the TEST pin twice when nRST is high and then pull nRST low.
	RST
	теят
	Note: This sequence is not subject to timing constraints and the appropriate level transitions are sufficient to trigger an exit from BSL mode.

MPY1	MPY32 Module				
Function	Save and Restore feature on MPY32 not functional				
Description	The MPY32 module uses the Save and Restore method which involves saving the multiplier state by pushing the MPY configuration/operand values to the stack before using the multiplier inside an Interrupt Service Routine (ISR) and then restoring the state by popping the configuration/operand values back to the MPY registers at the end of the ISR. However due to the erratum the Save and Restore operation fails causing the write operation to the OP2H register right after the restore operation to be ignored as it is not preceded by a write to OP2L register resulting in an invalid multiply operation.				
Workaround	None. Disable interrupts when writing to OP2L and OP2H registers.				
	Note: When using the C-compiler, the interrupts are automatically disabled while using the MPY32				
PMAP1	PMAP Module				
Function	Port Mapping Controller does not clear unselected inputs to mapped module.				
Description	The Port Mapping Controller provides the logical OR of all port mapped inputs to a module (Timer, USCI, etc). If the PSEL bit (PxSEL.y) of a port mapped input is cleared, then the logic level of that port mapped input is latched to the current logic level of the input. If the input is in a logical high state, then this high state is latched into the input of the logical OR. In this case, the input to the module is always a logical 1 regardless of the state of the selected input.				
Workaround	1. Drive input to the low state before clearing the PSEL bit of that input and switching to another input source.				
	or 2. Use the Port Mapping Controller reconfiguration feature, PMAPRECFG, to select inputs to a module and map only one input at a time.				
PMM9	PMM Module				
Function	False SVSxIFG events				
Description	The comparators of the SVS require a certain amount of time to stabilize and output a correct result once re-enabled; this time is different for the Full Performance versus the Normal mode. The time to stabilize the SVS comparators is intended to be accounted for by a built-in event-masking delay of 2 us when Full Performance mode is enabled.				
	However, the comparators of the SVS in Full Performance mode take longer than 2 us to stabilize so the possibility exists that a false positive will be triggered on the SVSH or SVSL. This results in the SVSxIFG flags being set and depending on the configuration of SVSxPE bit a POR can also be triggered.				
	Additionally when the SVSxIFGs are set, all GPIOs are tri-stated i.e. floating until the SVSx comparators are settled.				
	The SVS IFG's are falsely set under the following conditions:				
	1. Wakeup from LPM2/3/4 when SVSxMD = 0 (default setting) && SVSxFP=1. The SVSx comparators are disabled automatically in LPM2/3/4 and are then re-enabled on return to active mode.				
	2. SVSx is turned on in full performance mode (SVSxFP=1).				

www.ti.com	Detailed Bug Description
	3. A PUC/POR occurs after SVSx is disabled. After a PUC or POR the SVSx are enabled automatically but the settling delay does not get triggered. Based on SVSxPE bit this may lead to POR events until the SVS comparator is fully settled.
Workaround	For each of the above listed conditions the following workarounds apply:
	1. If the Full Performance mode is to be enabled for either the high- or low-side SVS comparators, the respective SVSxMD bits must be set (SVSxMD = 1) such that the SVS comparators are not temporarily shut off in LPM2/3/4. Note that this is equivalent to a 2 uA (typical) adder to the low power mode current, per the device-specific datasheet, for each SVSx that remains enabled.
	The SVSx must be turned on in normal mode (SVSxFP=0). It can be reconfigured to use full performance mode once the SVSx/SVMx delay has expired.
	3. Ensure that SVSH and SVSL are always enabled.
PMM10	PMM Module
Function	SVS/SVM flags disabled after Power Up Clear reset
Description	SVS/SVM interrupt flag functionality is disabled after a Power Up Clear (PUC) Reset if the SVS was disabled before the PUC reset was applied.
Workaround	A write access to the intended SVSx register after PUC re-enables the SVS & SVM interrupt flags.
PMM11	PMM Module
Function	MCLK comes up fast on exit from LPM3 and LPM4
Description	The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 us. This behavior is masked from affecting code execution by default: SVSL and SVML run in normal-performance mode and mask CPU execution for 150 us on wakeup from LPM3 and LPM4. However, when the low-side SVS and the SVM are disabled or are operating in full-performance mode (SVMLE = 0 and SVSLE = 0, or SVMLFP = 1 and SVSLFP = 1) AND MCLK is sourced from the internal DCO running over 4 MHz, 7 MHz, 11 MHz, or 14 MHz at core voltage levels 0, 1, 2, and 3, respectively, the mask lasts only 2 us. MCLK is, therefore, susceptible to run out of spec for 4 us.
Workaround	Set the MCLK divide bits in the Unified Clock System Control 5 Register (UCSCTL5) to divide MCLK by two prior to entering LPM3 or LPM4 (set DIVMx = 001). This prevents MCLK from running out of spec when the CPU wakes from the low-power mode. Following the wakeup from the low-power mode, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, and 3, respectively, before resetting DIVMx to zero and running MCLK at full speed [for example,delay_cycles(100)].
PMM12	PMM Module
Function	SMCLK comes up fast on exit from LPM3 and LPM4
Description	The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 us. When SMCLK is sourced by the DCO, it is not masked on exit from LPM3 or LPM4. Therefore, SMCLK exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 us. The increased frequency has the potential to change the expected timing behavior of peripherals that select SMCLK as the clock source.



Workaround	- Use XT2 as the SMCLK oscillator source instead of the DCO.
	or
	- Do not disable the clock request bit for SMCLKREQEN in the Unified Clock System Control 8 Register (UCSCTL8). This means that all modules that depend on SMCLK to operate successfully should be halted or disabled before entering LPM3 or LPM4. If the increased frequency prevents the proper function of an affected module, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before re-enabling the module [for example,delay_cycles(100)].
PMM14	PMM Module
Function	Increasing the core level when SVS/SVM low side is configured in full-performance mode causes device reset
Description	When the SVS/SVM low side is configured in full performance mode (SVSMLCTL.SVSLFP = 1), the setting time delay for the SVS comparators is ~2us. When increasing the core level in full-performance mode; the core voltage does not settle to the new level before the settling time delay of the SVS/SVM comparator expires. This results in a device reset.
Workaround	When increasing the core level; enable the SVS/SVM low side in normal mode (SVSMLCTL.SVSLFP=0). This provides a settling time delay of approximately 150us allowing the core sufficient time to increase to the expected voltage before the delay expires.
PMM15	PMM Module
Function	Device may not wake up from LPM2, LPM3, or LPM4
Description	Device may not wake up from LPM2, LPM3 or LMP4 if an interrupt occurs within 1 us after the entry to the specified LPMx; entry can be caused either by user code or automatically (for example, after a previous ISR is completed). Device can be recovered with an external reset or a power cycle. Additionally, a PUC can also be used to reset the failing condition and bring the device back to normal operation (for example, a PUC caused by the WDT).
	This effect is seen when:
	 A write to the SVSMHCTL and SVSMLCTL registers is immediately followed by an LPM2, LPM3, LPM4 entry without waiting the requisite settling time ((PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0)).
	or
	The following two conditions are met:
	- The SVSL module is configured for a fast wake-up or when the SVSL/SVML module is turned off. The affected SVSMLCTL register settings are shaded in the following table.



	SVSLE	SVSLMD SVSLFP		AM, LPM0/1 SVSL state	Manual SVSMLACE = 0 LPM2/3/4 SVSL State	Automatic SVSMLACE = 1 LPM2/3/4 SVSL State	Wakeup Time LPM2/3/4
SVSL	0	х	х	OFF	OFF	OFF	twake-up fast
	1	0	0	Normal	OFF	OFF	twake-up slow
	1	0	1	Full Performance	OFF	OFF	twake-up fast
	1	1	0	Normal	Normal	OFF	twake-up slow
	1	1	1	Full Performance	Full Performance	Normal	twake-up fast
SVML	SVMLE	SVM	I FP	AM, LPM0/1	Manual SVSMLACE = 0	Automatic SVSMLACE = 1	Wakeup Time
				SVML state	LPM2/3/4 SVML State	LPM2/3/4 SVML State	LPM2/3/4
	0	х		OFF	OFF	OFF	twake-up fast
	1	0		Normal	Normal	OFF	t _{WAKE-UP SLOW}
	1	1		Full Performance	Full Performance	Normal	twake-up fast

and

-The SVSH/SVMH module is configured to transition from Normal mode to an OFF state when moving from Active/LPM0/LPM1 into LPM2/LPM3/LPM4 modes. The affected SVSMHCTL register settings are shaded in the following table.

	SVSHE	SVSHMD SVSHFP		AM, LPM0/1 SVSH state	Manual SVSMHACE = 0 LPM2/3/4 SVSH State	Manual SVSMHACE = 1 LPM2/3/4 SVSH State
SVSH	0	х	х	OFF	OFF	OFF
	1	0	0	Normal	OFF	OFF
	1	0	1	Full Performance	OFF	OFF
	1	1	0	Normal	Normal	OFF
	1	1	1	Full Performance	Full Performance	Normal
SVMH	SVSHE SVM			AM, LPM0/1	Manual SVSMHACE = 0	Manual SVSMHACE = 1
	SVORE	SVMHFP		SVSH state	LPM2/3/4 SVSH State	LPM2/3/4 SVSH State
	0	х		OFF	OFF	OFF
	1	0		Normal	Normal	OFF
	1	1		Full Performance	Full Performance	Normal

Workaround

Any write to the SVSMxCTL register must be followed by a settling delay (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0) before entering LPM2, LPM3, LPM4.

and

1. Ensure the SVSx, SVMx are configured to prevent the issue from occurring by the following:

- Configure the SVSL module for slow wake up (SVSLFP = 0). Note that this will increase the wakeup time from LPM2/3/4 to twakeupslow (\sim 150 us).

or

- Do not configure the SVSH/SVMH such that the modules transition from Normal mode to an OFF state on LPM entry. Instead force the modules to remain ON even in LPMx. Note that this will cause increased power consumption when in LPMx.

Refer to the MSP430F5xx and MSP430F6xx Core Libraries (<u>SLAA448</u>) for proper PMM configuration functions.

Use the following function, PMM15Check (void), to determine whether or not the existing PMM configuration is affected by the erratum. The return value of the function is 1 if the configuration is affected, and 0 if the configuration is not affected.

unsigned char PMM15Check (void)

	{ // First check if SVSL/SVML is configured for fast wake-up
	if ((!(SVSMLCTL & SVSLE)) ((SVSMLCTL & SVSLE) && (SVSMLCTL & SVSLFP))
	(!(SVSMLCTL & SVMLE)) ((SVSMLCTL & SVMLE) && (SVSMLCTL & SVMLFP)))
	{ // Next Check SVSH/SVMH settings to see if settings are affected by PMM15
	if ((SVSMHCTL & SVSHE) && (!(SVSMHCTL & SVSHFP)))
	if ((!(SVSMHCTL & SVSHMD)) ((SVSMHCTL & SVSHMD) &&
	(SVSMHCTL & SVSMHACE)))
	return 1; // SVSH affected configurations
	}
	if ((SVSMHCTL & SVMHE) && (!(SVSMHCTL & SVMHFP)) && (SVSMHCTL & SVSMHACE))
	return 1; // SVMH affected configurations
	}
	return 0; // SVS/M settings not affected by PMM15
	}
	}
	If fast servicing of interrupts is required, add a 150us delay either in the interrupt service routine or before entry into LPM3/LPM4.
PMM17	PMM Module
PMM17 Function	
	PMM Module
Function	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the
Function	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage.
Function Description	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The VCORE accumulation is fixed by enabling the prolongation mechanism in software. The following lines of code need to be implemented before periodic execution of LPM-to-
Function Description	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The VCORE accumulation is fixed by enabling the prolongation mechanism in software. The following lines of code need to be implemented before periodic execution of LPM-to-AM-LPM. It is recommended to execute the code at program start:
Function Description	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The following lines of code need to be implemented before periodic execution of LPM-to-AM-LPM. It is recommended to execute the code at program start: ASM code:
Function Description	PHM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The VCORE accumulation is fixed by enabling the prolongation mechanism in software. The following lines of code need to be implemented before periodic execution of LPM-to-AM-LPM. It is recommended to execute the code at program start: ASM code: mov.w #0x9602, &0110h;
Function Description	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The following lines of code need to be implemented before periodic execution of LPM-to-AM-LPM. It is recommended to execute the code at program start: ASM code: mov.w #0x9602, &0110h; bis.w #0x0800, &0112h;
Function Description	PMM Module Vcore exceed maximum limit of 2.0V. If the device is switching between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, VCORE, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact but could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage. The accumulation of Vcore affects only older lot trace codes of mentioned revisions. The VCORE accumulation is fixed by enabling the prolongation mechanism in software. The following lines of code need to be implemented before periodic execution of LPM-to-AM-LPM. It is recommended to execute the code at program start: ASM code: mov.w #0x9602, &0110h; bis.w #0x0800, &0112h; C code:



www.ti.com	Detailed Bug Description			
	For detailed background information, affected LTCs and possible workaround(s) see Vcore Accumulation documentation in <u>SLAA505</u> .			
PMM18	PMM Module			
Function	PMM supply overvoltage protection falsely triggers POR			
Description	The PMM Supply Voltage Monitor (SVM) high side can be configured as overvoltage protection (OVP) using the SVMHOVPE bit of SVSMHCTL register. In this mode a POR should typically be triggered when DVCC reaches ~3.75V.			
	If the OVP feature of SVM high side is enabled going into LPM234, the SVM might trigger at DVCC voltages below 3.6V (~3.5V) within a few ns after wake-up. This can falsely cause an OVP-triggered POR. The OVP level is temperature sensitive during fail scenario and decreases with higher temperature (85 degC ~3.2V).			
Workaround	Use Adaptive mode (SVMACE=1). The SVM high side is inactive in LPM234.			
PMM20	PMM Module			
Function	Unexpected SVSL/SVML event during wakeup from LPM2/3/4 in fast wakeup mode			
Description	If PMM low side is configured to operate in fast wakeup mode, during wakeup from LPM2/3/4 the internal VCORE voltage can experience voltage drop below the corresponding SVSL and SVML threshold (recommendation according to User's Guide) leading to an unexpected SVSL/SVML event. Depending on PMM configuration, this event triggers a POR or an interrupt.			
	NOTE: As soon the SVSL or the SVML is enabled in Normal performance mode the device is in slow wakeup mode and this erratum does not apply.			
	In addition, this erratum has sporadic characteristic due to an internal asynchronous circuit. The drop of Vcore does not have an impact on specified device performance.			
Workaround	If SVSL or SVML is required for application (to observe external disruptive events at Vcore pin) the slow wakeup mode has to be used to avoid unexpected SVSL/SVML events. This is achieved if the SVSL or the SVML is configured in "Normal" performance mode (not disabled and not in "Full" Performance Mode).			
PORT15	PORT Module			
Function	In-system debugging causes the PMALOCKED bit to be always set			
Description	The port mapping controller registers cannot be modified when single-stepping or halting at break points between a valid password write to the PMAPWD register and the expected lock of the port mapping (PMAP) registers. This causes the PMAPLOCKED bit to remain set and not clear as expected.			
	Note: This erratum only applies to in-system debugging and is not applicable when operating in free-running mode.			
Workaround	Do not single step through or place break points in the port mapping configuration section of code.			

PORT16

Function

Description

www.ti.com
PORT Module
GPIO pins are driven low during device start-up
During device start-up, all of the GPIO pins are expected to be in the floating input state. Due to this erratum, some of the GPIO pins are driven low for the duration of boot code execution during device start-up, if an external reset event (via the RST pin) interrupted the previous boot code execution. Boot code is always executed after a BOR, and the duration of this boot code execution is approximately 500us.
For a given device family, this erratum affects only the GPIO pins that are not available in the smallest package device family member, but that are present on its larger package variants.
Note: This erratum does not affect the smallest package device variants in a particular

Workaround Ensure that no external reset is applied via the RST pin during boot code execution of the device, which occurs 1us after device start-up.

> Note: System application needs to account for this erratum in to ensure there is no increased current draw by the external components or damage to the external components in the system during device start-up

PORT19 PORT Module

Port interrupt may be missed on entry to LPMx.5 Function

device family.

If a port interrupt occurs within a small timing window (~1MCLK cycle) of the device entry Description into LPM3.5 or LPM4.5, it is possible that the interrupt is lost. Hence this interrupt will not trigger a wakeup from LPMx.5.

Workaround

None

RTC3 RTC A Module

Function Unreliable write to RTC register

A write access to the RTC registers (SEC, MIN, HOUR, DATE, MON, YEAR, DOW) may Description result in unexpected results. As a consequence the addressed register might not contain the written data, or some data can be accidentally written to other RTC registers.

Workaround Use the RTC library routines, available as F541x/F543x code examples on the MSP430 Code Examples page (www.ti.com/msp430 > Software > Code Examples), which use carefully aligned MOV instructions. Library is listed as RTC_Workaround.zip and includes both CCE and IAR example projects that show proper usage. Using this library, full access to RTC registers is possible.

RTC6 RTC_A Module

the step size of the RTC frequency adjustment is twice the specified size. Function

Description The step size of the RTC frequency adjustment is =4ppm/-8ppm. This is twice the size specified in the User's Guide.

> For up calibration this results in a step size per step of 8ppm (1024 cycles) instead of 4ppm (512 cycles). For down calibration this results in a step size per step of 4ppm (512 cycles) instead of 2ppm (256 cycles).



www.ti.com	Detailed Bug Description				
Workaround	Half the calibration value written into RTCCAL register to compensate the doubled step size.				
SYS10	SYS Module				
Function	BSL entry sequence is subject to specific timing requirements				
Description	The BSL entry sequence requires that the low phase of the TEST/SBWTCK pin does not exceed 15us. This timing requirement is faster than most PC serial ports can provide, as shown in the following picture. If this requirement is not met, the entry sequence fails and the SYSBSLIND is not set.				
	RST/NMI				
	TEST				
Workaround	An external hardware solution is recommended to provide the appropriate BSL entry sequence. See http://processors.wiki.ti.com/index.php/BSL_(MSP430) for recommendations on available BSL hardware. Note: The erroneous behavior is only applicable if the default TI USB BSL is replaced by				
	the TI UART BSL.				
SYS12	SYS Module				
Function	Invalid ACCVIFG when DVcc in the range of 2.4 to 2.6V				
Description	A Flash Access Violation Interrupt Flag (ACCVIFG) may be triggered by the Voltage Changed During Program Error bit (VPE) when DVcc is in the range of 2.4 to 2.6V. Although this behavior is expected according to the user's guide, the VPE does not signify an invalid flash operation has occured.				
	If the ACCVIE bit is set and a flash operation is executed in the affected voltage range, an unnecessary interrupt is requested. The bootstrap loader also cannot be used to execute write/erase flash operations in this voltage range, because it exits the flash operation and returns an error on an ACCVIFG event.				
Workaround	None				
SYS16	SYS Module				
Function	Fast Vcc ramp after device power up may cause a reset				
Description	At initial power-up, after Vcc crosses the brownout threshold and reaches a constant level, an abrupt ramp of Vcc at a rate $dV/dT > 1V/100$ us can cause a brownout condition to be incorrectly detected even though Vcc does not fall below the brownout threshold. This causes the device to undergo a reset.				
Workaround	Use a controlled Vcc ramp to power up the device.				

SYS18	SYS Module				
Function	USB registers are unlocked and ACCVIFG is set at start-up				
Description	During device start-up, an incorrect line of code in the start-up code causes the USB registers to remain unlocked and causes an access violation, setting ACCVIFG bit.				
	In the BSL430_Low_Level_Init code, the following line of code accesses USBKEY (incorrect register address) instead of USBKEYPID, causing an access violation setting ACCVIFG bit, and leaving the USB registers unlocked.				
	mov.w #0x0000, &USBKEY ; lock USB				
	The correct line of code should read:				
	mov.w #0x0000, &USBKEYPID ; lock USB correctly				
	Note: This code does not run when using the JTAG debugger - the behavior only appears when running standalone.				
Workaround	1. Load the latest version of the USB BSL from Custom BSL Download				
	OR				
	2. Load a non-USB or custom BSL				
	OR 3. Erase the BSL				
	3. Elase tile DSL				
TAB23	TIMER_A/TIMER_B Module				
Function	TAxR/TBxR read can be corrupted when TAxR/TBxR = TAxCCR0/TBxCCR0				
Description	When a timer in Up mode is stopped and the counter register (TAxR/TBxR) is equal to the TAxCCR0/TBxCCR0 value, a read of the TAR/TBR register may return an unexpected result.				
Workaround	1. Use 'Up/Down' mode instead of 'Up' mode				
	OR				
	2. In 'Up' mode, use the timer interrupt instead of halting the counter and reading out the value in TAxR/TBxR				
	OR				
	3. When halting the timer counter in 'Up' mode, reinitialize the timer before starting to run again.				
UCS6	UCS Module				
Function	USCI source clock does not turn off in LPM3/4 when UART is idle				
Description	The USCI clock source (ACLK/SMCLK) remains enabled in LPM3 and LPM4 when the USCI is configured in UART mode and the communication is idle (UCSWRST = 0 but no TX or RX currently executing). This is contrary to the expected automatic clock activation described in the User's Guide and can lead to higher current consumption in low power modes, depending on the oscillator that feeds ACLK / SMCLK.				
Workaround	Use the oscillator that is already active in LPM3 (ACLK) to source the USCI and utilize the low-power baud rate generator (UCOS16 = 0). For UART baud rates where a fast SMCLK sourced by the internal DCO is required use LPM0 instead of LPM3.				

UCS7	UCS Module				
Function	DCO drifts when servicing short ISRs when in LPM0 or exiting active from ISRs for shor periods of time				
Description	The FLL uses two rising edges of the reference clock to compare against the DCO frequency and decide on the required modifications to the DCOx and MODx bits. If the device is in a low power mode with FLL disabled (LPM0 with DCO not sourcing ACLK/SMCLK or LPM2, LPM3, LPM4 where SCG1 bit is set) and enters a state which enables FLL (enter ISR from LPM0/LPM2 or exit active from ISRs) for a period less than 3x reference clock cycles, then the FLL will cause the DCO to drift.				
	This occurs because the FLL immediately begins comparing an active DCO with its reference clock and making the respective modifications to the DCOx and MODx bits. If the FLL is not given sufficient time to capture a full reference clock cycle (2 x reference clock periods) and adjust accordingly (1 x reference clock period), then the DCO will keep drifting each time the FLL is enabled.				
Workaround	(1) If DCO is not sourcing ACLK or SMCLK in the application, use LPM1 instead of LPM0 to make sure FLL is disabled when interrupt service routine is serviced.				
	(2) When exiting active from ISRs, insert a delay of at least 3 x reference clock periods. To save on power budget, the 3 x reference clock periods could also be spent in LPM0 with TimerA or TimerB using ACLK/SMCLK sourced from DCO. This way, the FLL and DCO are still active in LPM0.				
UCS9	UCS Module				
Function	Digital Bypass mode prevents entry into LPM4				
Description	When entering LPM4, if an external digital input applied to XT1 in HF mode or XT2 is not turned off, the PMM does not switch to low-current mode causing higher than expected power consumption.				
Workaround	Before entering LPM4:				
	(1) Switch to a clock source other than external bypass digital input. OR				
	(2) Turn off external bypass mode (UCSCTL6.XT1BYPASS = 0).				
UCS10	UCS Module				
Function	Modulation causes shift in DCO frequency				
Description	When the FLL is enabled, the DCO frequency can be tracked automatically by modifying the DCOx and MODx bits. The MODx bits switch between the frequency selected by the DCO bits and the next-higher frequency set by (DCO + 1). The erroneous behavior is seen when the FLL is tracking close to a DCO step boundary and the MOD counter is expected to rollover, but instead the DCO bits increment and the MOD bits decrement. This causes the DCO to shift by up to 12% and remain at an increased frequency until approximately 15 REFCLK cycles have elapsed. The frequency reverts to the expected value immediately afterward.				
	For example, the modulator moves from $DCOx = n$ and $MODx = 31$ to $DCOx = n + 1$				
	and MODx = 30, causing a large increase in the DCO frequency.				
	Applications could be impacted as follows:				



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	When using the DCO frequency for asynchronous serial communication and timer operation, the effect can be seen as corrupted data or incorrect timing events.
Workaround	(1) Turn off the FLL.
	Or
	(2) Implement a Software FLL, comparing the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture and tuning the value of the DCO and MOD bits periodically.
	Or
	(3) Execute the following sequence in periodic intervals.
	1. Disable peripherals sourced by the DCO such as UART and Timer.
	2. Turn on the FLL.
	3. Wait the worst case settling time of 32 X 32 X fFLLREFCLK to allow it to lock to the target frequency.
	4. Turn off the FLL.
	5. Compare the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture.
	- If the DCO frequency is higher than expected, repeat from step (2) until the
	frequency reaches to the expected range.
	- Else proceed with code execution.
	See the application report UCS10 Guidance <u>SLAA489</u> for more detailed information regarding working with this erratum. This erratum does not affect proper operation of the CPU when MCLK = DCO/FLL and is set to the maximum clock frequency specified in the device datasheet.
UCS11	UCS Module
Function	Modifying UCSCTL4 clock control register triggers an erroneous clock source request
Description	Changing the SELM/SELS/SELA bits in the UCSCTL4 register might trigger the respective clocks to select an incorrect clock source which requests the XT1/XT2 clock. If the crystals are not present at XT1/XT2 or present but not yet configured in the application firmware, then the respective XT1/XT2 fault flag is falsely set.
Workaround	Clear all the fault flags in UCSCTL7 register once after changing any of the SELM/SELS/SELA bits in the UCSCTL4 register.
USB4	USB Module
Function	USB control registers cannot be modified during USB Function Reset when FRSTE = 1
Description	If the function reset connection enable (FRSTE) bit in the USBCTL register is set and the USB host asserts reset over the USB bus, then the USB control registers cannot be modified until the host reset is de-asserted. The FRSTE bit is used to enable the USB function reset to reset of all internal logic of the USB module and is used to reduce the software overhead of USB reset handling.
Workaround	Clear the FRSTE bit inside the RSTRIFG interrupt service routine before reconfiguring the USB control registers, and set the FRSTE bit at the beginning of SUSRIFG, SETUPIFG, IEPIFG.EP0, and OEPIFG.EP0 interrupt service routines.



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	NOTE: TI supplied stacks implement this software workaround			
USB6	USB Module			
Function	Endpoint0 STALL bit can be cleared during USBIEPCNFG_0/ USBOEPCNFG_0 register access			
Description	According to the MSP430F5xx Family User's Guide (SLAU208), the STALL bit in the Endpoint0 configuration register should be set by software when there is either an unsupported control request or a control request fail or an endpoint halt, and this bit is automatically cleared by the next setup transaction. In correct operation, the hardware clearing of the Endpoint0 STALL bit should not occur when the configuration registers USBIEPCNFG_0/USBOEPCNFG_0 are being accessed even though the next set-up transaction required to clear the STALL bit has occurred. Rather, the hardware clear of the STALL bit should wait until the access is finished, and then clear the bit.			
	However due to the erratum, if the next setup transaction occurs while the USBIEPCNFG_0/USBOEPCNFG_0 registers are being accessed, the STALL bit will be cleared immediately. This can be a problem during write accesses; for example, if the application tries to set the STALL bit and the next set-up transaction has cleared it. In this case, a valid STALL condition might be missed.			
Workaround	 Set the STALL bit inside the SETUP ISR. The STALL bit is automatically cleared on entering SETUP ISR so the user does not need to check it is cleared before setting STALL = 1. 			
	or			
	- Poll the STALL bit to verify it is cleared, then set STALL = 1.			
	NOTE: The USB stacks supplied by TI implement the first software workaround.			
USB8	USB Module			
Function	USB PLL may fail to initialize when DCO is not used			
Description	If the DCO is not used or does not source any clock in the system, the PLL may not initialize properly, leading to a "bus error" NMI when the CPU attempts to access USB memory. Under certain conditions, the PLL requires the DCO to be active in order to initialize properly. If any of the system clocks (MCLK, SMCLK, ACLK) are derived from the DCO during PLL initialization, this condition is satisfied and the PLL initializes in a stable manner.			
Workaround	 Configure one of the system clocks to use the DCO for normal operation. (In most applications, it's convenient to source MCLK from the DCO.) 			
	or			
	 If it's necessary to use a clock configuration that doesn't include the DCO, then briefly activate it, then de-activate it. This should be done after setting the UPLLEN bit but before polling the USBPLLIR flags. The code below shows a simplified PLL initialization procedure. (In the MSP430 USB API Stacks, this is performed in USB_enable().) 			
	USBPLLCTL = UPLLEN; // Enable PLL			
	// Add the following code to enable the DCO, then immediately revert back			
	// to the original clock settings for the application. This is long			
	// enough to allow PLL initialization to proceed. The actual UCSCTL4			
	// settings depend on the application's clock requirements.			
	UCSCTL4 = SELAREFOCLK + SELSXT2CLK + SELMDCOCLK; // Enable the			



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	DCO			
	UCSCTL4 = SELA_REFOCLK + SELS_XT2CLK + SELM_XT2CLK; // Revert back			
	//Wait for the PLL to settle			
	do {			
	USBPLLIR = 0x0000; // Clear the flags			
	for (i =0; i < 400; i++); // Wait for flags to set if not stable yet			
	}while (USBPLLIR != 0);			
	// PLL is now stable			
USB9	USB Module			
Function	VBUS detection may fail after powerup			
Description	In rare cases, some USB-equipped MSP430 devices may experience a failure in the bandgap that aids in detecting the presence of 5 V on the VBUS pin. Two primary effects of this are:			
	- The USBBGVBV bit fails to show the presence of a valid voltage on the VBUS pin.			
	and			
	- The USB LDOs fail to start.			
Workaround	This error state can be "reset" by clearing all of the bits in the USBPWRCTL register, which disables the USB LDOs, among other actions. The bits can then be set again normally, and the device functions properly.			
	This has been added to the USB_Init() function in v3.10 and later of the MSP430 USB API. Therefore, this problem is automatically addressed in applications that use the API.			
	However, if the integrated 3.3-V USB LDO (the output of the VUSB pin) is used to power the device's DVCC pin, as in many bus-powered applications, and if the rare bandgap error occurs, the CPU fails to power up, because the USB LDO fails to operate. The problem might be resolved by cycling power to the VBUS pin; for example, if the end user responds to the failure by unplugging and replugging the USB cable. The bandgap failure is also known to occur more often with slow DVCC ramps > 200 ms; for example, when there is excessive capacitance on the DVCC pin, in excess of what the USB specification allows. However, the only sure way to prevent the problem from occurring in the first place is to avoid making DVCC power reliant on VUSB.			
USB10	USB Module			
Function	USB interface may begin to babble when a rare timing event occurs between the USB host and MSP430 software execution			
Description	When the host sends a SETUP packet for an IN transaction, the SETUPIFG bit always gets set by hardware, and the USB ISR is triggered. While SETUPIFG is high, the host's attempts to continue the transaction with IN packets are automatically NAKed.			
	When the SETUP packet has been decoded and the IN data prepared, the USB ISR clears the SETUPIFG bit. But if it happens to do so within the 2nd CRC bit of an IN packet from the host, the USB module enters an errant state and can begin to "babble" (endless transmission to the host, irrespective of the protocol). The errant state can be cleared by resetting the module with the USB_EN bit; but there's no way for software to reliably detect the condition.			
	Since the 2nd CRC bit is only an 83ns window, the problem is extremely rare. However, since the timing of IN packets relative to their preceding SETUP packets can vary			

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	according to the host's timing, there's no way to ensure for certain that it will never happen.				
Workaround	If the problem behavior occurs, and if the MSP430 is bus-powered, the user may naturally unplug/re-plug the device's USB connection. If this occurs, the behavior will be corrected because power to the MSP430 will be cycled. After this, it's unlikely the problem will occur again soon, since the failure is usually rare.				
	The behavior can be prevented altogether by clearing the UBME bit immediately before clearing SETUPIFG, and setting it again immediately after:				
	USBIEPCNF_0 &= ~EPCNF_UBME; // Clear ME to gate off SETUPIFG clear event USBOEPCNF_0 &= ~EPCNF_UBME; // Clear ME to gate off SETUPIFG clear event USBIFG &= ~SETUPIFG; // clear the interrupt bit USBIEPCNF_0 = EPCNF_UBME; // Set ME to continue with normal				
	operation USBOEPCNF_0 = EPCNF_UBME; // Set ME to continue with normal operation				
	This workaround is reliable and effective. However, as a side effect, it results in the creation of orphan tokens on the USB interface. Although the workaround is field-tested, and no problems have been reported with these orphan packets, it is recommended to use the workaround only if the errata behavior is problematic for the application in question.				
USCI26	USCI Module				
Function	Tbuf parameter violation in I2C multi-master mode				
Description	In multi-master I2C systems the timing parameter Tbuf (bus free time between a stop condition and the following start) is not guaranteed to match the I2C specification of 4.7us in standard mode and 1.3us in fast mode. If the UCTXSTT bit is set during a running I2C transaction, the USCI module waits and issues the start condition on bus release causing the violation to occur.				
	Note: It is recommended to check if UCBBUSY bit is cleared before setting UCTXSTT=1.				
Workaround	None				
USCI30	USCI Module				
Function	I2C mode master receiver / slave receiver				
Description	When the USCI I2C module is configured as a receiver (master or slave), it performs a double-buffered receive operation. In a transaction of two bytes, once the first byte is moved from the receive shift register to the receive buffer the byte is acknowledged and the state machine allows the reception of the next byte.				
	If the receive buffer has not been cleared of its contents by reading the UCBxRXBUF register while the 7th bit of the following data byte is being received, an error condition may occur on the I2C bus. Depending on the USCI configuration the following may occur:				
	 If the USCI is configured as an I2C master receiver, an unintentional repeated start condition can be triggered or the master switches into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case. 				
	2) If the USCI is configured as I2C slave receiver, the slave can switch to an idle state				



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stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine will notify the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the 7th bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition will not occur.

Workarounda) The error condition can be avoided altogether by servicing the UCBxRXIFG in a
timely manner. This can be done by (a) servicing the interrupt and ensuring
UCBxRXBUF is read promptly or (b) Using the DMA to automatically read bytes from
receive buffer upon UCBxRXIFG being set.

OR

b) In case the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLLOW is set for atleast three USCI bit clock cycles i.e. 3 X t(BitClock).

Note that the last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes follow the workaround:

Code flow for workaround

(1) Enter RX ISR for reading receiving bytes

(2) Check if UCSCLLOW.UCBxSTAT == 1

(3) If no, repeat step 2 until set

(4) If yes, repeat step 2 for a time period > 3 x t (BitClock) where t (BitClock) = 1/f (BitClock)

(5) If window of 3 x t(BitClock) cycles has elapsed, it is safe to read UCBxRXBUF

USCI31 **USCI** Module **Function** Framing Error after USCI SW Reset (UCSWRST) Description While receiving a byte over USCI-UART (with UCBUSY bit set), if the application resets the USCI module (software reset via UCSWRST), then a framing error is reported for the next receiving byte. 1. If possible, do not reset USCI-UART during an ongoing receive operation; that is, Workaround when UCBUSY bit is set. 2. If the application software resets the USCI module (via the UCSWRST bit) during an ongoing receive operation, then set and reset the UCSYNC bit before releasing the software USCI reset. Workaround code sequence: bis #UCSWRST, &UCAxCTL1 ; USCI SW reset :Workaround begins bis #UCSYNC, &UCAxCTL0 ; set synchronous mode bic #UCSYNC, &UCAxCTL0 ; reset synchronous mode :Workaround ends bic #UCSWRST, &UCAxCTL1 ; release USCI reset

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USCI34	USCI Module				
Function	I2C multi-master transmit may lose first few bytes.				
Description	In an I2C multi-master system (UCMM =1), under the following conditions:				
	(1)the master is configured as a transmitter (UCTR =1)				
	AND				
	(2)the start bit is set (UCTXSTT =1);				
	if the I2C bus is unavailable, then the USCI module enters an idle state where it waits and checks for bus release. While in the idle state it is possible that the USCI master updates its TXIFG based on clock line activity due to other master/slave communication on the bus. The data byte(s) loaded in TXBUF while in idle state are lost and transmit pointers initialized by the user in the transmit ISR are updated incorrectly.				
Workaround	Verify that the START condition has been sent (UCTXSTT =0) before loading TXBUF with data.				
USCI35	USCI Module				
Function	Violation of setup and hold times for (repeated) start in I2C master mode				
Description	In I2C master mode, the setup and hold times for a (repeated) START, $t_{SU,STA}$ and $t_{HD,STA}$ respectively, can be violated if SCL clock frequency is greater than 50kHz in standard mode (100kbps). As a result, a slave can receive incorrect data or the I2C bus can be stalled due to clock stretching by the slave.				
Workaround	If using repeated start, ensure SCL clock frequencies is < 50kHz in I2C standard mode (100 kbps).				
WDG4	WDT_A Module				
Function	The WDT failsafe can be disabled				
Description	The UCS is capable of masking clock requests (ACLK, SMCLK, MCLK) from peripheral modules; see request enable (REQEN) bits in the UCS control register, UCSCTL8.				
	The clock request logic of the UCS is used by the WDT module to ensure a fail-safe clock source in all low-power modes. Therefore, de-asserting the request enable bit of the watchdog clock source (xCLKREQEN = 0) allows the respective clock to be disabled upon entry into a low-power mode. Without an active clock source, the WDT timer stops incrementing and a watchdog event will not occur.				
	None				

Document Revision History

5 Document Revision History

Changes from family erratasheet to device specific erratasheet.

- 1. Errata JTAG21 was removed
- 2. Errata RTC4 was removed
- 3. Revision H was added
- 4. PMM17 is impacting silicon revision E

Changes from device specific erratasheet to document Revision A.

- 1. Errata DMA10 was added to the errata documentation.
- 2. Errata PORT19 was added to the errata documentation.
- 3. Errata PMM18 was added to the errata documentation.
- 4. Errata RTC6 was added to the errata documentation.
- 5. Errata SYS18 was added to the errata documentation.

Changes from document Revision A to Revision B.

- 1. DMA10 Workaround was updated.
- 2. DMA10 Description was updated.

Changes from document Revision B to Revision C.

- 1. Errata BSL7 was added to the errata documentation.
- 2. Silicon Revision I was added to the errata documentation.
- 3. Errata RTC3 was added to the errata documentation.
- 4. DMA10 Description was updated.

Changes from document Revision C to Revision D.

- 1. Errata BSL6 was added to the errata documentation.
- 2. DMA10 Description was updated.
- 3. DMA10 Function was updated.

Changes from document Revision D to Revision E.

- 1. DMA10 Description was updated.
- 2. BSL6 Workaround was updated.
- 3. MPY1 Description was updated.
- 4. Errata EEM23 was added to the errata documentation.
- 5. Errata CPU43 was added to the errata documentation.

Changes from document Revision E to Revision F.

- 1. SYS16 Description was updated.
- 2. CPU43 Description was updated.
- 3. Errata USCI34 was added to the errata documentation.
- 4. Device TLV Hardware Revision information added to erratasheet.

Changes from document Revision F to Revision G.

- 1. Errata PMM20 was added to the errata documentation.
- 2. Errata USCI35 was added to the errata documentation.

Changes from document Revision G to Revision H.

- 1. BSL7 Workaround was updated.
- 2. BSL7 Function was updated.
- 3. Errata USB10 was added to the errata documentation.



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